MMDL301T1G

Silicon Hot-Carrier Diodes

Schottky Barrier Diode

These devices are designed primarily for high−efficiency UHF and VHF detector applications. They are readily adaptable to many other fast switching RF and digital applications. They are supplied in an inexpensive plastic package for low−cost, high−volume consumer and industrial/commercial requirements. They are available in a Surface Mount package.

Features

- Extremely Low Minority Carrier Lifetime − 15 ps (Typ)
- Very Low Capacitance − 1.5 pF (Max) @ V_R = 15 V
- Low Reverse Leakage − I_R = 13 nAdc (Typ)
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

MAXIMUM RATINGS (T_J = 125°C unless otherwise noted)

Rating	Symbol	Value	Unit
Reverse Voltage	V_R	30	V

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Total Device Dissipation FR−5 Board, (Note 1) @T_A = 25°C Derate above 25°C	P_D	200 1.57	mW mW/°C
Thermal Resistance, Junction−to−Ambient	$R_{\theta JA}$	635	°C/W
Junction and Storage Temperature Range	T_J, T_{stg}	−55 to +150	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. FR−5 Minimum Pad

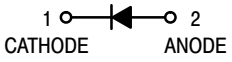
ELECTRICAL CHARACTERISTICS (T_A = 25°C unless otherwise noted)

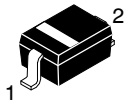
Characteristic	Symbol	Min	Typ	Max	Unit
Reverse Breakdown Voltage (I_R = 10 μA)	$V_{(BR)R}$	30	−	−	V
Total Capacitance (V_R = 15 V, f = 1.0 MHz) Figure 1	C_T	−	0.9	1.5	pF
Reverse Leakage (V_R = 25 V) Figure 3	I_R	−	13	200	nAdc
Forward Voltage (I_F = 1.0 mAdc) Figure 4	V_F	−	0.38	0.45	Vdc
Forward Voltage (I_F = 10 mAdc) Figure 4	V_F	−	0.52	0.6	Vdc

ON Semiconductor®

http://onsemi.com

30 VOLTS SILICON HOT−CARRIER DETECTOR AND SWITCHING DIODES





PLASTIC
SOD−323
CASE 477
STYLE 1

MARKING DIAGRAM

4T = Device Code
M = Date Code*
▪ = Pb−Free Package

(Note: Microdot may be in either location)
*Date Code orientation may vary depending upon manufacturing location.

ORDERING INFORMATION

Device	Package	Shipping†
MMDL301T1G	SOD−323 (Pb−Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

TYPICAL ELECTRICAL CHARACTERISTICS

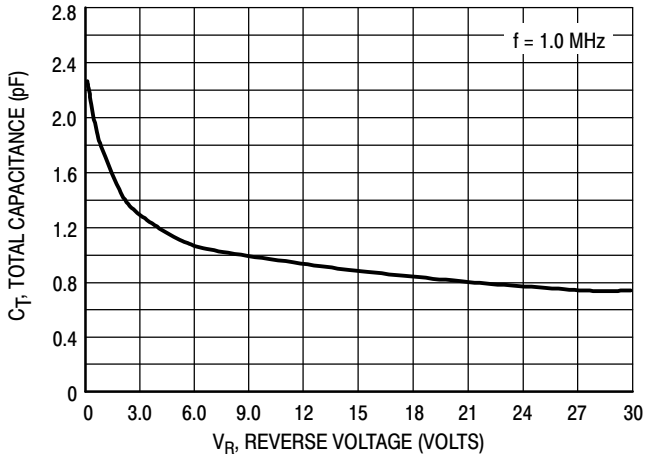


Figure 1. Total Capacitance

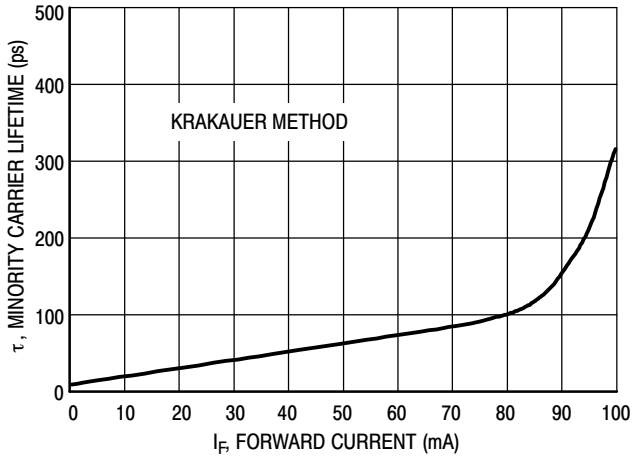


Figure 2. Minority Carrier Lifetime

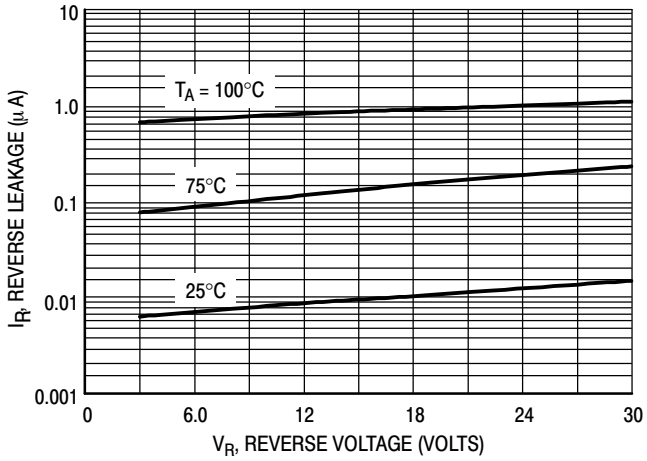


Figure 3. Reverse Leakage

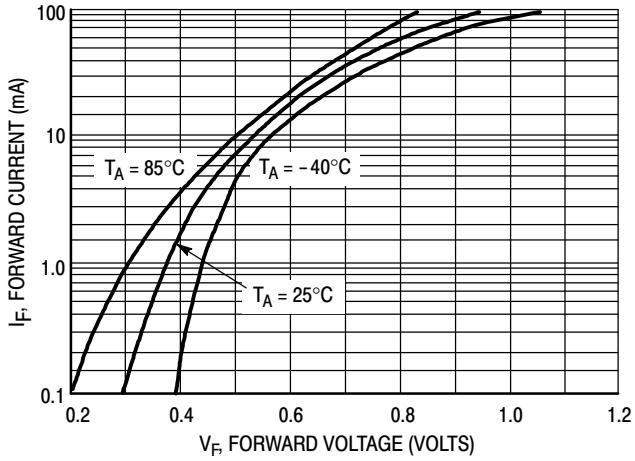


Figure 4. Forward Voltage

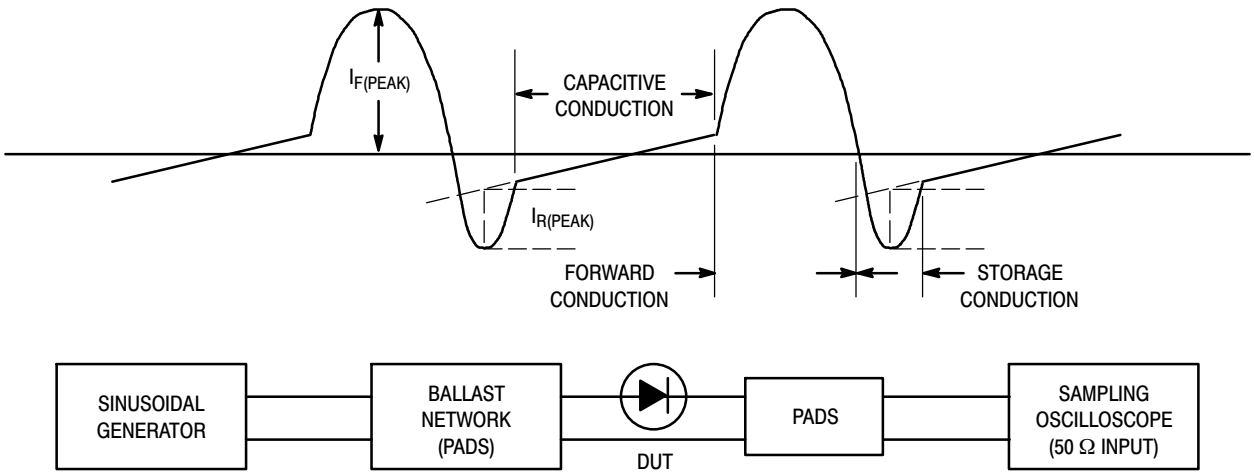
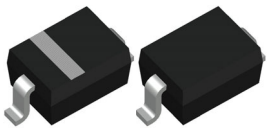


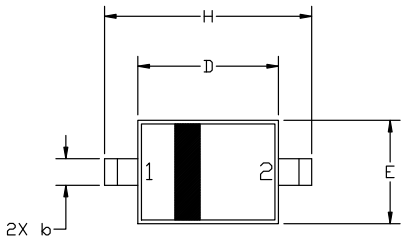
Figure 5. Krakauer Method of Measuring Lifetime

MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

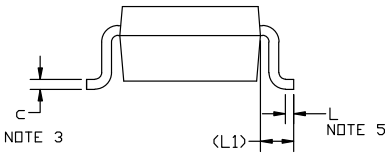


SOD−323 1.70x1.25x0.85
CASE 477
ISSUE K

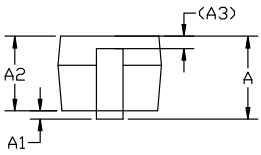
DATE 11 MAR 2024



TOP VIEW



SIDE VIEW

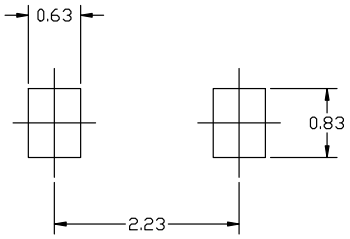


END VIEW

NOTES:

1. DIMENSIONING AND TOLERANCING AS PER ASME Y14.5M, 2018.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. LEAD THICKNESS SPECIFIED PER L/F DRAWING WITH SOLDER PLATING.
4. DIMENSIONS A AND B DO NOT INCLUDE MOLD FLASH, PROTRUSIONS OR GATE BURRS.
5. DIMENSION L IS MEASURE FROM END OF RADIUS.

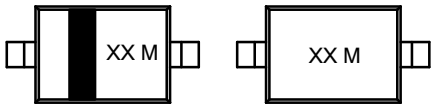
DIM	MILLIMETERS		
	MIN.	NOM.	MAX.
A	0.80	0.90	1.00
A1	0.00	0.05	0.10
A2	0.75	0.85	0.95
A3	0.15 (REF)		
b	0.25	0.32	0.4
c	0.09	0.12	0.18
D	1.60	1.70	1.80
E	1.15	1.25	1.35
H	2.30	2.50	2.70
L	0.08	---	---
L1	0.40 (REF)		



RECOMMENDED MOUNTING FOOTPRINT

*For additional information on our Pb−Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference manual, SOLDERRM/D.

GENERIC MARKING DIAGRAM*



STYLE 1 STYLE 2

XX = Specific Device Code
M = Date Code

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “▪”, may or may not be present. Some products may not follow the Generic Marking.

STYLE 1:
PIN 1. CATHODE (POLARITY BAND)
2. ANODE

STYLE 2:
NO POLARITY

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DESCRIPTION:	SOD−323 1.70x1.25x0.85	PAGE 1 OF 1

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